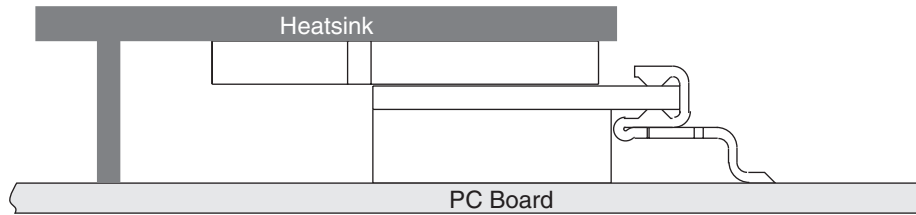


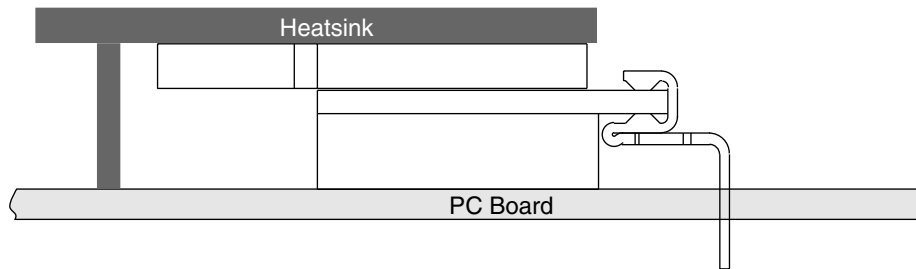
MECHANICAL SUGGESTIONS FOR POWERSIP SURFACE MOUNT PACKAGES

SIP02, SIP03: DIFFERENT BENDING AND MOUNTING OPTIONS



CAUTION

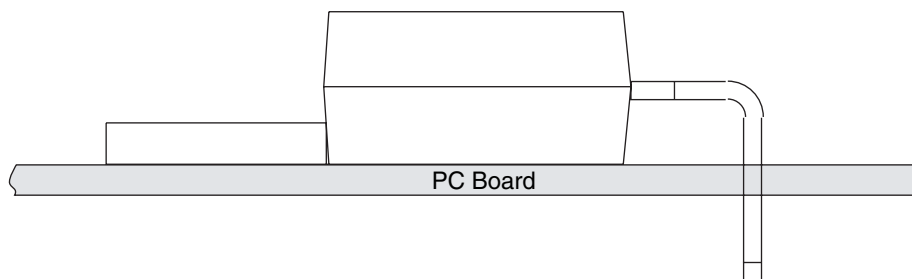
The heat sink has to be mechanically attached to the same PC board as the device, close to the device if possible. Not doing so may result in catastrophic failure.



CAUTION

The heat sink has to be mechanically attached to the same PC board as the device, close to the device if possible. Not doing so may result in catastrophic failure.

SIP12: DIFFERENT BENDING AND MOUNTING OPTIONS



REFER TO PACKAGES DATA SHEET FOR DIMENSIONS